

## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application.

### **COMPLETE LISTING OF CLAIMS:**

Claims 1-14 : (Canceled)

Claim 15 : (New) A circuit assembly, comprising:

- a) a circuit board;
- b) at least one circuit component wire bonded to the circuit board;
- c) a base plate on which the circuit board is fixed; and
- d) a filling body of a material locally filled and hardened in a gap between

the base plate and the circuit board.

Claim 16 : (New) The circuit assembly according to claim 15, in that the filling body is located at a hole in the circuit board.

Claim 17 : (New) The circuit assembly according to claim 16, in that the filling body engages the hole.

Claim 18 : (New) The circuit assembly according to claim 16, in that the filling body extends into the gap beyond edges of the hole.

Claim 19 : (New) The circuit assembly according to claim 16, in that the hole is free from metallization.

Claim 20 : (New) The circuit assembly according to claim 15, in that the hardened material is an adhesive.

Claim 21 : (New) The circuit assembly according to claim 20, in that the adhesive is electrically conductive.

Claim 22 : (New) The circuit assembly according to claim 15, in that the filling body is located adjacent to at least one bond pad.

Claim 23 : (New) The circuit assembly according to claim 22, in that at least two filling bodies are located at different sides of the at least one bond pad.

Claim 24 : (New) A method of manufacturing a circuit assembly, comprising the steps of:

a) fixing a circuit board and at least one circuit component on a base plate;

b) applying at least one bonding wire between the at least one circuit component and a bond pad of the circuit board; and

c) introducing a hardenable material into a gap between the circuit board and the base plate after the fixing step, and before the applying step, and allowing the hardenable material to harden in the gap.

Claim 25 : (New) The method according to claim 24, in that the introducing step is performed using capillary force.

Claim 26 : (New) The method according to claim 24, in that the introducing step is performed by introducing the hardenable material into the gap through a hole in the circuit board.

Claim 27 : (New) The method according to claim 24, in that the hardenable material is an adhesive introduced into the gap and applied to at least one of the circuit board and the base plate for cementing the at least one circuit component in a same step.

Claim 28 : (New) The method according to claim 24, in that the applying step is performed by ultrasonic welding.